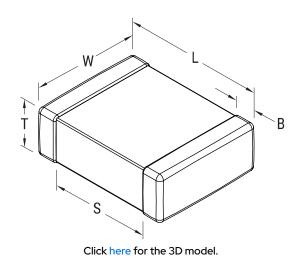


C0805C131JBGACTU

Aliases (C0805C131JBGAC7800) SMD Comm COG HV, Ceramic, 130 pF, 5%, 630 VDC, COG, SMD, MLCC, Ultra-Stable, Low Loss, Class I, 0805, 0.7 mm



General Information	
Series	SMD Comm COG HV
Style	SMD Chip
Description	SMD, MLCC, Ultra-Stable, Low Loss, Class I
Features	Ultra-Stable, Low Loss, Class I
RoHS	Yes
Termination	Tin
Marking	No
AEC-Q200	No
Typical Component Weight	14 mg
Shelf Life	78 Weeks
MSL	1

Dimensions	
Chip Size	0805
L	2mm +/-0.2mm
W	1.25mm +/-0.2mm
Т	1.25mm +/-0.15mm
S	0.7mm MIN
В	0.5mm +/-0.25mm

2500

Packaging Quantity

Т	1.25mm +/-0.15mm	Voltage DC
S	0.7mm MIN	Dielectric Withstanding Volta
В	0.5mm +/-0.25mm	Temperature Range
		Temp. Coefficient
Packaging Specifications		Capacitance Change with
Packaging	T&R, 180mm, Plastic Tape	Reference to +25°C and 0 VD Applied (TCC)

Specifications	
Capacitance	130 pF
Measurement Condition	1 MHz 1.0Vrms
Tolerance	5%
Voltage DC	630 VDC
Dielectric Withstanding Voltage	945 VDC
Temperature Range	-55/+125°C
Temp. Coefficient	COG
Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC)	30 ppm/C, 1MegaHz 1.0Vrms
Dissipation Factor	0.1% 1 MHz 1.0Vrms
Aging Rate	0% Loss/Decade Hour
Insulation Resistance	100 GOhms

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